

# SOT995-2

plastic thermal enhanced low profile quad flat package; no leads; 48 terminals; resin based

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFN48R
<b>Package type industry code</b>	HLQFN48R
<b>Package style descriptive code</b>	HLQFN (thermal enhanced low profile quad flatpack; no leads)
<b>Package style suffix code</b>	R (resin based)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-12-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	1.1	-	1.15	1.25	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	48	-	

## 2. Package outline

Fig. 1. Package outline HLQFN48R (SOT995-2)



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### 3. Legal information

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